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VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM)

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In cooperation with:

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The EMLC 2010 Program Committee and The Local Committee:

Please find the members of the International Steering Committee of the EMLC on the website: www.emlc2010.com

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VDE/VDI-GESELLSCHAFT
MIKROELEKTRONIK,
MIKRO- UND FEINWERKTECHNIK



Call for Papers

The 26th European Mask and Lithography Conference EMLC 2010

January 18 – 20, 2010
Minatec Conference Center
Grenoble, France

www.EMLC2010.com



The VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM) and UBC Microelectronics in cooperation with AEPI, BACUS, CEA/LETI, Crolles Alliance, MINATEC, PMJ, SEMI-Europe, SPIE and Toppan Photomasks, are pleased to announce the

**26th European Mask and Lithography
Conference, EMLC2010**

**at the MINATEC Conference Center
Grenoble, France**

January 18 - January 20, 2010

The focus of this three-day conference is “state-of-the-art” of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results. This is the second time the EMLC will be held in France.

Conference Schedule:

The conference will start on Monday, January 18, 2010 at 01:00 pm with a Keynote Session.

The Poster Reception is planned for Monday, 05:30 pm.

The conference will continue with regular sessions on Tuesday, January 19, and Wednesday, January 20.

Technical Exhibition:

On Tuesday and Wednesday will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. To take part in this Technical Exhibition, please return the **enclosed registration form** to the conference chairperson as soon as possible, since exhibition space is limited.

**Conference Chairperson and
Exhibition Organization:**

Dr. Uwe Behringer,
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D-72119 Ammerbuch, Germany

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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. The abstracts should include at least one full page of text (minimum of 1000 words), the use of figures is encouraged.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

More information is provided at

www.emlc2010.com

Please send your abstract as a **MS-Word®** file to the Conference Chair, Dr. Uwe Behringer uwe.behringer.ubc@t-online.de, and to the Program Chairs, Dr. Wilhelm Maurer, wilhelm.maurer@infineon.com and Jacques Waelpoel, Jacques.waelpoel@asml.com

Deadline for Abstracts: September 28, 2009

By submitting an abstract you agree to

- Present your work in person at the conference
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by October 1, 2009; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please, send the original of the manuscript a.s.a.p., latest by

January 5, 2010

All manuscripts will be subject to a critical peer review before they are accepted as VDE publication. The VDE/GMM is in contact with SPIE for an additional publication in the SPIE Digital Library.

Please note: Late submissions may not be published.

Information on the format of the manuscripts and further details is also provided at the EMLC2010 conference web site: www.emlc2010.com

Conference Topics:

Presentations are solicited for the following and related topics:

Mask Manufacturing:

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business:

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application:

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies:

- EUV Materials, Tools & Processes
- EUV Mask Infrastructure
- NIL
- Direct Write / Maskless Technologies

Mask and Lithography Equipment

(Cover picture: Courtesy of Toppan Photomasks)

Please be aware that the information in this flyer is subject to change without notice!